

MIDEM 2012
48th International Conference on
Microelectronics, Devices and Materials
with the workshop on
CERAMIC MICROSYSTEMS



*Society for Microelectronics,
Electronic Components and Materials*

NAMASTE
CENTRE OF EXCELLENCE



SLOVENIAN RESEARCH AGENCY

OTOČEC, Slovenia, 19–21 Sept 2012

<http://www.term-krka.si/en/otocec/hotel/sport/>

www.midem-drustvo.si/conf2012

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Kosec Marija, Jožef Stefan Institute, Slovenia and CoE NAMASTE, Slovenia

Workshop Chair:

Darko Belavič, IN.Medica, Slovenia and CoE NAMASTE, Slovenia

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Miro Zeman, TU Delft, The Netherlands
Andrej Žemva, University of Ljubljana, Faculty of electrical engineering, Slovenia

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Darko Belavič, IN.Medica, Slovenia and CoE NAMASTE, Slovenia
Polona Šorli, MIDEM, Slovenia
Hana Uršič Nemevšek, Jožef Stefan Institute, Slovenia
Slavko Amon, University of Ljubljana, Faculty of electrical engineering, Slovenia

CALL FOR PAPERS

MIDEM 2012 Conference provides a forum for exchanging ideas, discussing research results and presenting practical applications in the areas of microelectronics, device design, fabrication techniques, thin and thick films and materials.

MIDEM 2012 Conference is organised by MIDEM, Society for Microelectronics, Electronic Components and Materials, Ljubljana, Slovenia and co-organized by Centre of Excellence NAMASTE, Ljubljana, Slovenia.

Topics of interest include but are not limited to:

- ✓ Novel monolithic and hybrid circuit processing techniques,
- ✓ New device and circuit design,
- ✓ Process and device modelling,
- ✓ Semiconductor physics,
- ✓ Sensors and actuators,
- ✓ Electromechanical devices, Microsystems and Nanosystems,
- ✓ Optoelectronics,
- ✓ Photovoltaic devices,
- ✓ New electronic materials and applications,
- ✓ Electronic materials science and technology,
- ✓ Materials characterization techniques,
- ✓ Reliability and failure analysis,
- ✓ Education in microelectronics, devices and materials.

Abstract and paper submission:

Prospective authors are cordially invited to submit 1/2-1 page abstract before **June 1st, 2012**. Please, identify the corresponding author with complete mailing address, phone and fax numbers and e-mail address.

After notification of acceptance (**June 22nd, 2012**), the authors are asked to prepare a full paper version of six pages maximum. Papers should be in black and white. Full paper deadline in PDF and DOC electronic format is: **August 24th, 2012**.

Important dates:

Abstract deadline: June 1st, 2012 (1/2-1 page abstract)

Notification of acceptance: June 22nd, 2012

Deadline for final version of manuscript: August 24th, 2012

Registration and payment of registration fee deadline: September 12th, 2012

Conference and Workshop location:

The conference and workshop will be held in the Hotel Šport, SI-8222 Otočec, Slovenia
<http://www.term-krka.si/en/otocec/hotel/sport/>

For further information please visit MIDEM 2012 web page:

www.midem-drustvo.si/conf2012

INVITED SPEAKER OF THE CONFERENCE

Paul Muralt, Ceramics Laboratory, École Polytechnique Fédérale de Lausanne (EPFL), CH-1015 Lausanne, Switzerland

Energy Harvesting with Piezoelectric Thin Film Micro Devices: Status and Promises

INVITED SPEAKERS OF THE WORKSHOP ON CERAMIC MICROSYSTEMS

Leszek J. Golonka, Faculty of Microsystem Electronics and Photonics, Wrocław University of Technology, Wybrzeże Wyspiańskiego 27, 50-370 Wrocław, Poland
LTCC Fluidic Microsystems

Thomas Maeder, Laboratoire de Production Microtechnique (LPM), École Polytechnique Fédérale de Lausanne (EPFL), CH-1015 Lausanne, Switzerland
3D Structuration of LTCC and Related Technologies for Thermal Management and Microfluidic Structures

W. Kinzy Jones, Department of Mechanical and Materials Engineering, Florida International University, Miami, FL 33199, USA
Cofired Platinum/Alumina Microsystems for Implantable Medical Applications

Raul Bermejo, Montanuniversität Leoben, Institut für Struktur- und Funktionskeramik, Leoben, Austria

Mechanical properties of Low Temperature Co-fired Ceramics: Testing Methodologies for Strength Characterization

Uwe Partsch, Fraunhofer Institute for Ceramic Technologies and Systems, Winterbergstrasse 28, D-01277 Dresden, Germany
LTCC-based Sensors for Mechanical Quantities

Goran Radosavljević, Department of Applied Electronics Materials, Institute of Sensor and Actuators Systems, Vienna University of Technology, Gusshausstrasse 27-29, A-1040 Vienna, Austria;
Resonant Sensors Realized in LTCC-technology for Wireless Monitoring of Physical Parameters

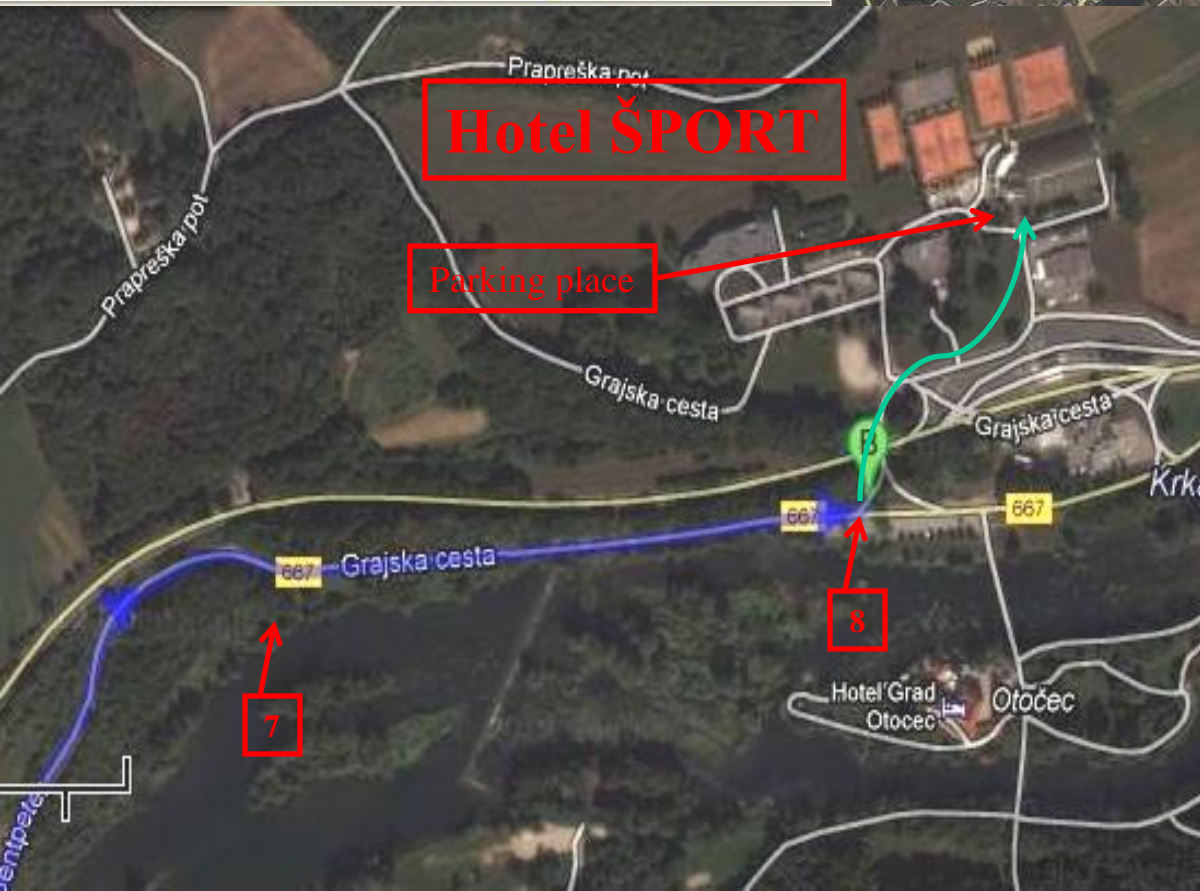
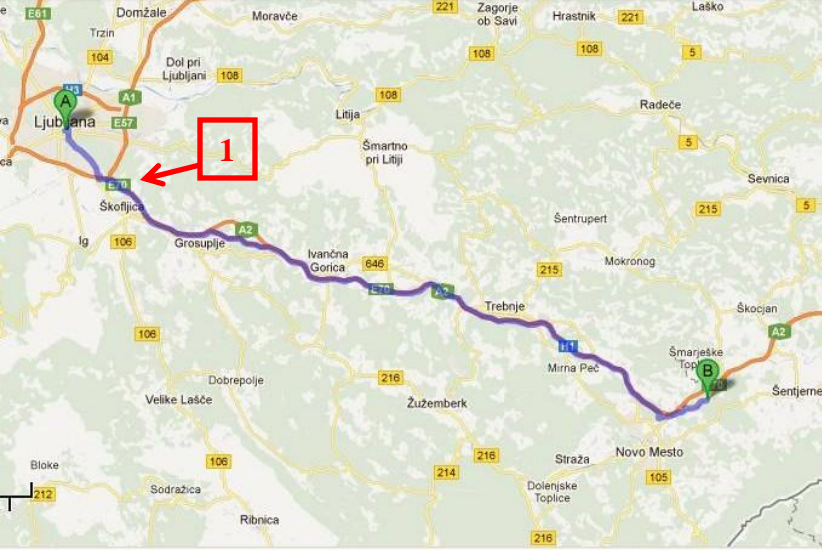
Franz Bechtold, VIA electronic GmbH, Robert-Friese-Strasse 3, D-07629 Hermsdorf, Germany;
Innovation Steps Towards a Novel and Cost Efficient LTCC Packaging Technology for High end Applications



Due to the increased number of papers, Oral and Poster Sessions will be prepared. Therefore we kindly ask authors to indicate in their Abstract if Oral or Poster presentation is suggested. However, all contributions, oral or poster, will be published in the conference proceedings.

In addition to the technical papers we also invite researchers and innovators from industry and academia to present an overview of their R&D activities in the Poster Session. These overviews will improve the discussion and exchange of multidisciplinary ideas between participants. Eventual printed materials will be added as a supplement to the conference materials.

We kindly ask you to express your interest for this kind of presentation before September 5th 2012.



- 1** When in Ljubljana, drive on the road E70 and follow the signs **Novo mesto**.
- 2** Take the **EXIT NOVO MESTO VZHOD** and drive towards **Metlika/Črnomelj/Dolenjske Toplice/Otočec**.
- 3** Take the **SECOND** exit at the roundabout and follow the road 448.
- 4** Take the **FIRST** exit at the second roundabout (just drive straight forward).
- 5** Take the **SECOND** turn at the third roundabout
- 6** Turn **RIGHT** on the road 667
- 7** Continue your way on the road 667
- 8** Turn slightly left and continue your way towards parking .